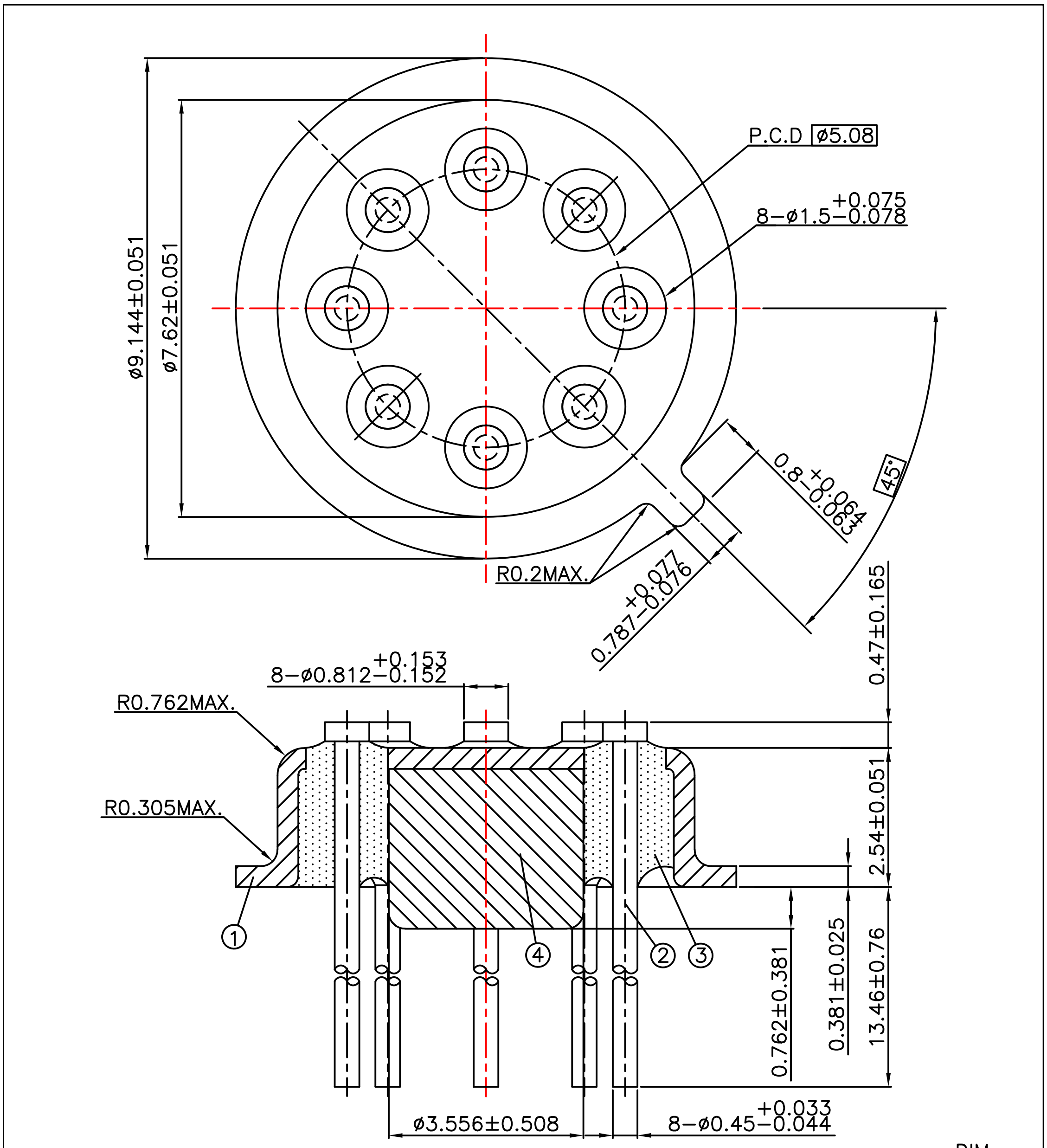
SSM P/N HDR00557



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REV	DATE	DSGN	CHECK	APPR	DESCRIPTION

ITEM	DESCRIPTION	DWG NO.	MATERIAL	QTY
4	STAND OFF		GLASS CERAMIC	1
3	GLASS		HARD GLASS	1
2	LEAD		KOVAR	8
1	EYELET		KOVAR	1

MATERIAL

FINISH
See notes 1.

NOTE
Spectrum
Semiconductor
Materials, Inc.

DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE
					TO−5/8PIN

PROJ 3RD ANGLE	SCALE	DRAWING NO.
	10:1	KR5475 2/4

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Notes.

1. Finish
   Full gold 1.27umMIN. over 2.54umMIN. Electrolytic nickel under plating.
   1) Plating thickness : Controlled on top of the post.
   2) Measuring method : X-ray fluorescence machine.

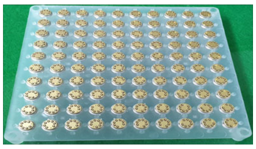
2. Packaging method.

2-1. Packaging material

	Transportation box	Tray	Vacuum bag	Air cap	Silicagel
Packing material	Carton box	CBX-148	Plastic pack	Air cap	Silicagel
Size	275X555X250	130X130X12	136X272X430	210X310X15	4g
Quantity(8,640pcs)	1	152	8	Suitable	Suitable

2-2. Packaging method

1) Put 100 pcs parts in 2 carrier.



2) The carrier containing the parts is piled 9 carrier,
   and empty carrier is put on the top.(total 19 carrier)

3) The carrier containing a parts of a 19 pile is put into Plastic bag
   with silica gel.

4) Operate 1) to 3) method 8 times repeatedly.
   (vacuumed Plastic bags - total of 8)

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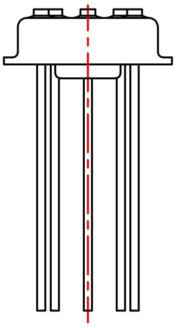
5) 8 Plastic bags are put Transportation box.

6) Tapping the outside box.

3. No coning



					MATERIAL	FINISH	NOTE
REV	DATE	DSGN	CHECK	APPR	DESCRIPTION		

DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE TO-5/8PIN

	PROJ 3RD ANGLE	SCALE	DRAWING NO. KR5475 4/4